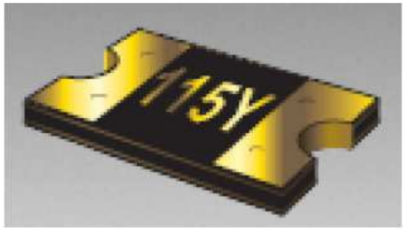
MATERIAL DECLARATION SHEET

BOURNS®

Material	MF-MSMF
Product Line	Multifuse
Revision Date	Apr.28, 2016
Revision	B
RoHS Compliant	Yes



No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0008432	1333-86-4	3.77%	3.77%
2	Copper plating	Copper	0.0016212	7440-50-8	7.24%	7.24%
3	Foil	Copper	0.0107250	7440-50-8	47.90%	50.42%
		Nickel	0.0005645	7440-02-0	2.52%	
4	PCB Foil	Copper	0.0013630	7440-50-8	6.09%	6.09%
5	Polymer	Polyethylene Homopolymer	0.0007470	9002-88-4	3.34%	3.34%
		Proprietary Additives	0.0000010		0.00%	
6	Prepreg	Epoxy	0.0038512	35948-25-5	17.20%	28.66%
		Glass fiber	0.0025672	65997-17-3	11.46%	
7	Packing-Carrier Tape	Polystyrece	N/A	9003-53-6		
		Polyethylene Homopolymer	N/A	9002-88-4		
8	Packing-Cover Tape	Polyethylene terephthalate	N/A	25038-59-9		
		Polyethylene Homopolymer	N/A	9002-88-4		
9	Soldering plating	Nickel	0.0001066	7440-02-0	0.47%	0.48%
		Gold	0.0000013	7440-57-5	0.01%	
		Total Weight (%)				

Total weight (grams)	0.0223912	Total	100%	100%